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PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Satoshi TAKANO

Application No.: 09/819,696

Docket No.: 109107

Filed: March 29, 2001

For: SEMICONDUCTOR MANUFACTURING METHOD, SUBSTRATE PROCESSING
METHOD, AND SEMICONDUCTOR MANUFACTURING APPARATUS



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REQUEST FOR CORRECTION OF PALM RECORDS

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Attached is a photocopy of the original filing receipt on which errors have been corrected in red. These errors are being brought to the attention of the Patent and Trademark Office so that it may correct its records.

Respectfully submitted,

James A. Oliff
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Date: July 30, 2001

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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
09/819,690	03/29/2001	2812	1000	109107	7	8	5

CONFIRMATION NO. 3148

UPDATED FILING RECEIPT



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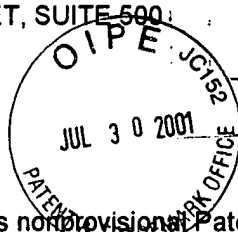
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Applicant(s)

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→ NAKANO-KU

→ Assignment for Published Patent Application
HITACHI KOKUSAI ELECTRIC INC.

Domestic Priority data as claimed by applicant

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JAPAN 2000-91642 03/29/2000

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Projected Publication Date: 10/04/2001

N n-Publication Request: No

Early Publication Request: No

Title

Semiconductor manufacturing method, substrate processing method, and semiconductor manufacturing apparatus

Preliminary Class

438



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Bib Data Sheet

CONFIRMATION NO. 3148

SERIAL NUMBER 09/819,690	FILING DATE 03/29/2001 RULE	CLASS 438	GROUP ART UNIT 2812	ATTORNEY DOCKET NO. 109107
APPLICANTS Satoshi Takano, Nakand-Ku, JAPAN; ** CONTINUING DATA ***** ** FOREIGN APPLICATIONS ***** JAPAN 2000-91642 03/29/2000 JAPAN 2001-60136 03/05/2001				
IF REQUIRED, FOREIGN FILING LICENSE GRANTED ** 05/05/2001				
Foreign Priority claimed <input checked="" type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 (a-d) conditions <input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after Allowance Verified and Acknowledged <u> </u> Examiner's Signature Initials		STATE OR COUNTRY JAPAN	SHEETS DRAWING 7	TOTAL CLAIMS 8
INDEPENDENT CLAIMS 5				
ADDRESS 25944 25944				
TITLE Semiconductor manufacturing method, substrate processing method, and semiconductor manufacturing apparatus				
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